

KOH Etching System

Features

The molten KOH etching is a useful method for revealing the etch pits of SiC wafer or GaN wafer.

This system is capable of KOH etching process safely and automatically.



Specifications

MODEL	ETC-6001F	ETC-8001F
Crucible size	ϕ 200×H169(t2)	ϕ 250×H190(t2)
Wafer size	1×6" ϕ	1×8" ϕ
Maximum heating temperature	700°C	
Temp. control stability	±1°C	
Wafer holder lift	auto	
Wafer holder rotation	max 10rpm	
Crucible shutter	manual	
Power Supply	1 ϕ 200V 20A	1 ϕ 200V 30A
Exhaust port diameter	ϕ 100	
System size	W750×D650×H1650	W1000×D930×H2200
System weight	190kg	350kg
Option	Signal tower	